INTEGRATED CIRCUITS

DATA SHEET

74ABT540Octal buffer, inverting (3-State)

Product specification Supersedes data of 1996 Oct 08 IC23 Data Handbook





Octal buffer, inverting (3-State)

74ABT540

FEATURES

- Octal bus interface
- 3-State buffers
- Live insertion/extraction permitted
- Efficient pinout to facilitate PC board layout
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec JC40.2 Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Power-up 3-State

DESCRIPTION

The 74ABT540 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT540 device is an octal inverting buffer that is ideal for driving bus lines. The device features input and outputs on opposite sides of the package to facilitate printed circuit board layout.

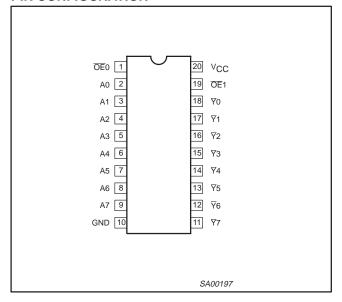
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay An to Ÿn	$C_L = 50pF; V_{CC} = 5V$	3.1	ns
C _{IN}	Input capacitance	$V_I = 0V \text{ or } V_{CC}$	3	pF
C _{OUT}	Output capacitance	Outputs disabled; V _O = 0V or V _{CC}	7	pF
I _{CCZ}	Total supply current	Outputs disabled; V _{CC} = 5.5V	50	μΑ

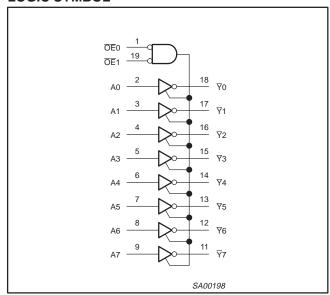
ORDERING INFORMATION

ONDERNING IN ORMATION				
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	-40°C to +85°C	74ABT540 N	74ABT540 N	SOT146-1
20-Pin plastic SO	-40°C to +85°C	74ABT540 D	74ABT540 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT540 DB	74ABT540 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT540 PW	74ABT540PW DH	SOT360-1

PIN CONFIGURATION



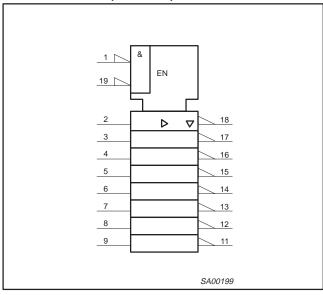
LOGIC SYMBOL



Octal buffer, inverting (3-State)

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LOGIC SYMBOL (IEEE/IEC)



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION		
2, 3, 4, 5, 6, 7, 8, 9	A0 – A7	Data inputs		
18, 17, 16, 15, 14, 13, 12, 11	7 0 − 7 7	Data outputs		
1, 19	ŌĒ0, ŌĒ1	Output enables		
10	GND	Ground (0V)		
20	V _{CC}	Positive supply voltage		

FUNCTION TABLE

	INPUTS		OUTPUTS
OE0	OE1	An	₹n
L L X H	L L H X	L H X X	H L Z Z

H = High voltage level

L = Low voltage level

X = Don't care Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		−0.5 to +7.0	V
I _{IK}	DC input diode current	V ₁ < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	−0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
 The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

74ABT540

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	ITS	UNIT
		Min	Max	
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Ta	_{mb} = +25	°C		: –40°C 85°C	UNIT
			Min	Тур	Max	Min	Max	
V _{IK}	Input clamp voltage	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	2.5	2.9		2.5		V
V _{OH}	High-level output voltage	$V_{CC} = 5.0V$; $I_{OH} = -3mA$; $V_I = V_{IL}$ or V_{IH}	3.0	3.4		3.0		V
		$V_{CC} = 4.5V$; $I_{OH} = -32mA$; $V_I = V_{IL}$ or V_{IH}	2.0	2.4		2.0		V
V _{OL}	Low-level output voltage	$V_{CC} = 4.5V$; $I_{OL} = 64mA$; $V_I = V_{IL}$ or V_{IH}		0.42	0.55		0.55	V
I _I	Input leakage current	$V_{CC} = 5.5V; V_I = GND \text{ or } 5.5V$		±0.01	±1.0		±1.0	μΑ
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V$; V_I or $V_O \le 4.5V$		±5.0	±100		±100	μΑ
I _{PU} /I _{PD}	Power-up/down 3-State output current ³	V_{CC} = 2.1V; V_{O} = 0.5V; V_{I} = GND or V_{CC} ; V_{OE} = Don't care		±5.0	±50		±50	μА
I _{OZH}	3-State output High current	$V_{CC} = 5.5V$; $V_{O} = 2.7V$; $V_{I} = V_{IL}$ or V_{IH}		5.0	50		50	μΑ
I _{OZL}	3-State output Low current	$V_{CC} = 5.5V; V_O = 0.5V; V_I = V_{IL} \text{ or } V_{IH}$		-5.0	-50		-50	μΑ
I _{CEX}	Output High leakage current	$V_{CC} = 5.5V$; $V_O = 5.5V$; $V_I = GND$ or V_{CC}		5.0	50		50	mA
Io	Output current ¹	$V_{CC} = 5.5V; V_O = 2.5V$	-50	-100	-180	-50	-180	mA
I _{CCH}		$V_{CC} = 5.5V$; Outputs High, $V_I = GND$ or V_{CC}		50	250		250	μΑ
I _{CCL}	Quiescent supply current	$V_{CC} = 5.5V$; Outputs Low, $V_I = GND$ or V_{CC}		24	30		30	mA
I _{CCZ}		V_{CC} = 5.5V; Outputs 3-State; V_I = GND or V_{CC}		50	250		250	μА
		Outputs enabled, one input at 3.4V, other inputs at $V_{\rm CC}$ or GND; $V_{\rm CC}$ = 5.5V		0.5	1.5		1.5	mA
Δl _{CC}	Additional supply current per input pin ²	Outputs 3-State, one data input at 3.4V, other inputs at V _{CC} or GND; V _{CC} = 5.5V		0.5	50		50	μА
		Outputs 3-State, one enable input at 3.4V, other inputs at $V_{\rm CC}$ or GND; $V_{\rm CC}$ = 5.5V		0.5	1.5		1.5	mA

- 1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- This is the increase in supply current for each input at 3.4V.
 This parameter is valid for any V_{CC} between 0V and 2.1V, with a transition time of up to 10msec. From V_{CC} = 2.1V to V_{CC} = 5V ± 10% a transition time of up to 100μsec is permitted.

Octal buffer, inverting (3-State)

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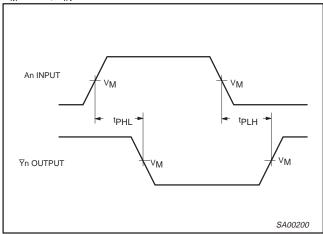
AC CHARACTERISTICS

GND = 0V; t_R = t_F = 2.5ns; C_L = 50pF, R_L = 500 Ω

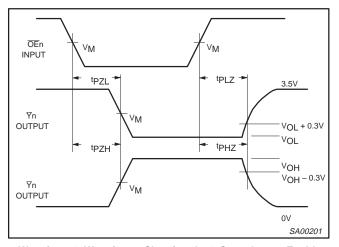
SYMBOL	PARAMETER	WAVEFORM	T _e	_{amb} = +25° 'CC = +5.0°	C V	T _{amb} = -40° V _{CC} = +5.	UNIT	
			Min	Тур	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay An to ₹n	1	1.0 1.0	2.9 3.1	4.1 4.3	1.0 1.0	4.8 4.8	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.1 1.1	4.1 4.6	4.9 5.8	1.1 1.1	5.9 6.4	ns
t _{PHZ}	Output disable time from High and Low level	2	1.5 1.2	3.6 2.9	6.8 5.7	1.5 1.2	7.3 6.2	ns

AC WAVEFORMS

 $V_{M} = 1.5V$, $V_{IN} = GND$ to 3.0V

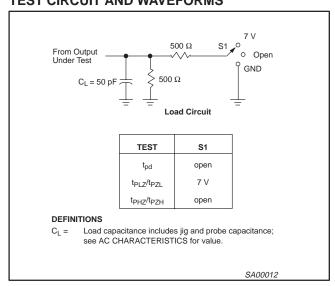


Waveform 1. Waveforms Showing the Input (An) to Output $(\overline{Y}n)$ Propagation Delays



Waveform 2. Waveforms Showing the 3-State Output Enable and Disable Times

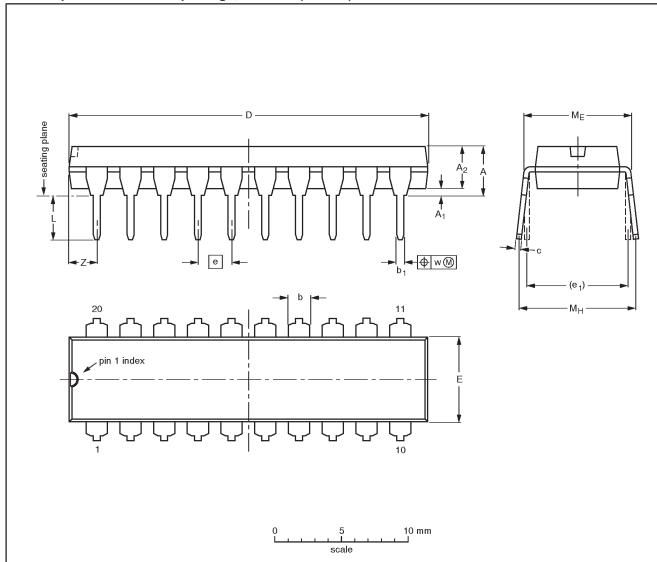
TEST CIRCUIT AND WAVEFORMS



74ABT540

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

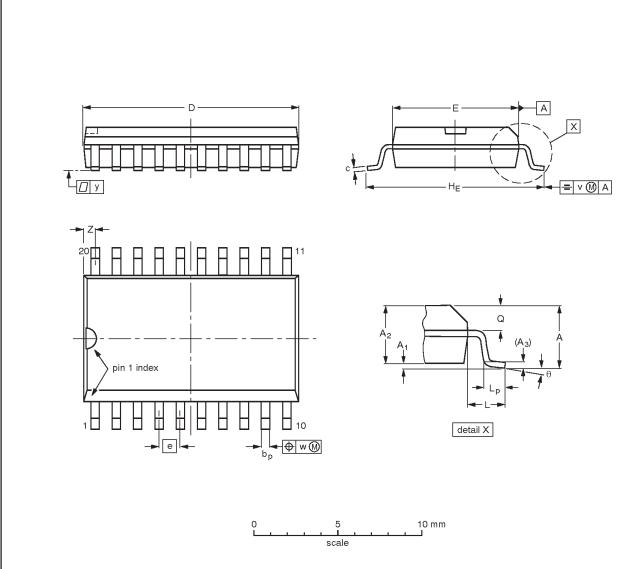
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT146-1			SC603			92-11-17 95-05-24

74ABT540

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	O	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	٧	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	o°

Note

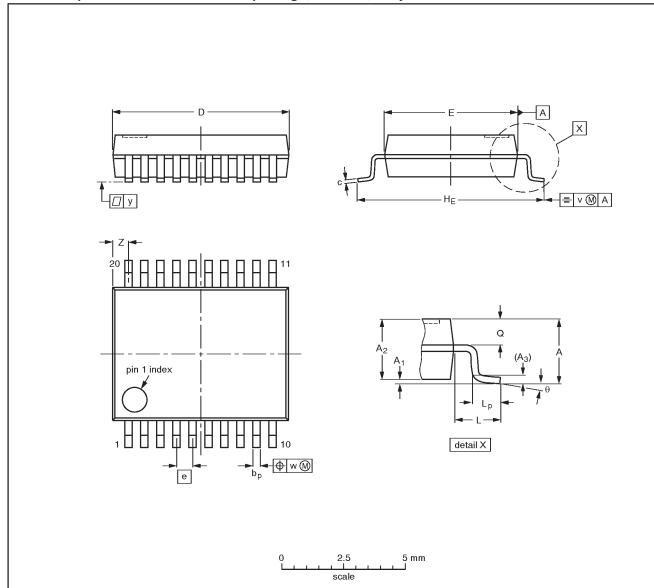
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	C EIAJ		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				-92-11-17 95-01-24	

74ABT540

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

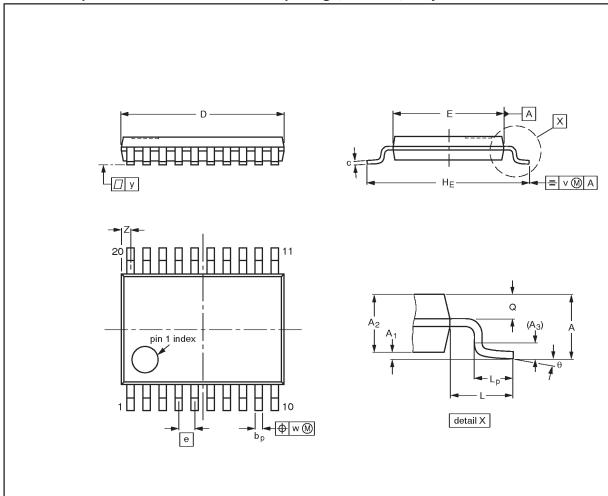
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT339-1		MO-150AE			93-09-08 95-02-04	

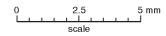
Octal buffer, inverting (3-State)

74ABT540

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	рb	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Œ	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1550E DATE
SOT360-1		MO-153AC			-93-06-16- 95-02-04

Octal buffer, inverting (3-State)

74ABT540

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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print code Date of release: 05-96

Document order number: 9397-750-03471

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